

# Industrial AI Technology in Manufacturing

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# Today

1 Why Manufacturing AI?

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2 Computer vision ML for manufacturing

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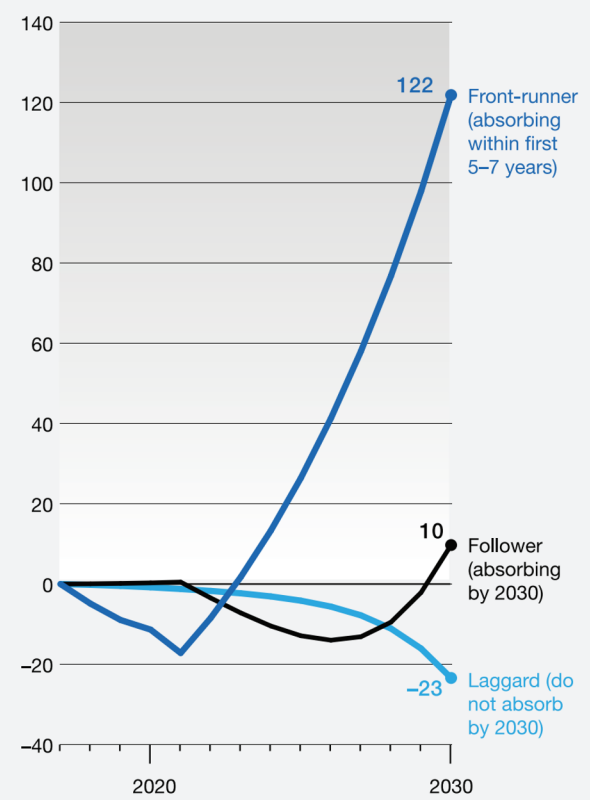
3 Time-series ML for manufacturing

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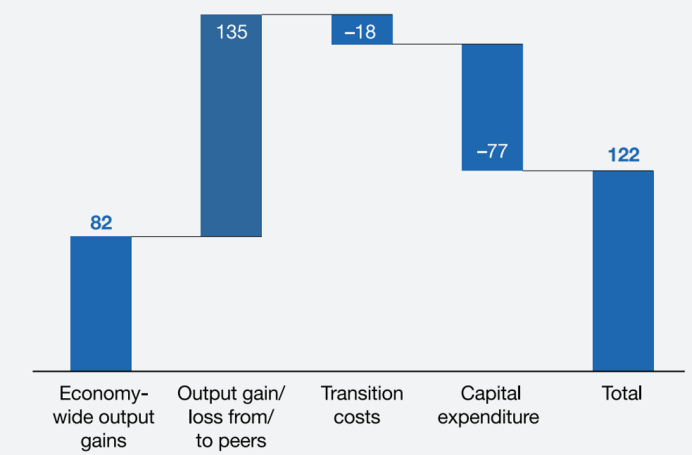
4 Difficulties with time-series ML in manufacturing

Fast AI adoption  
 WILL create **way**  
 larger economic  
 gains

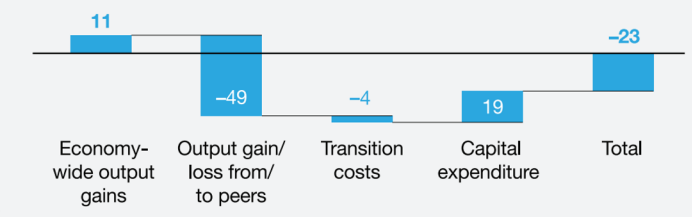
Relative changes in cash flow by AI-adoption cohort, cumulative % change per cohort



Front-runner breakdown, % change per cohort



Laggard breakdown, % change per cohort



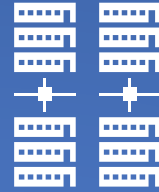
Note: Numbers are simulated figures to provide directional perspectives rather than forecasts.

\* Source: McKinsey Global Institute Analysis (2019)

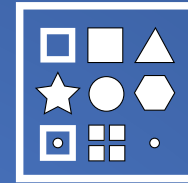
## Data Characteristics

Virtuous (or Vicious) Cycle

Data-centric AI



Volume



Variety



Velocity



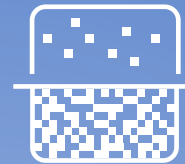
FatData



Shift/drift



Imbalance



Quality



Nonlinearity

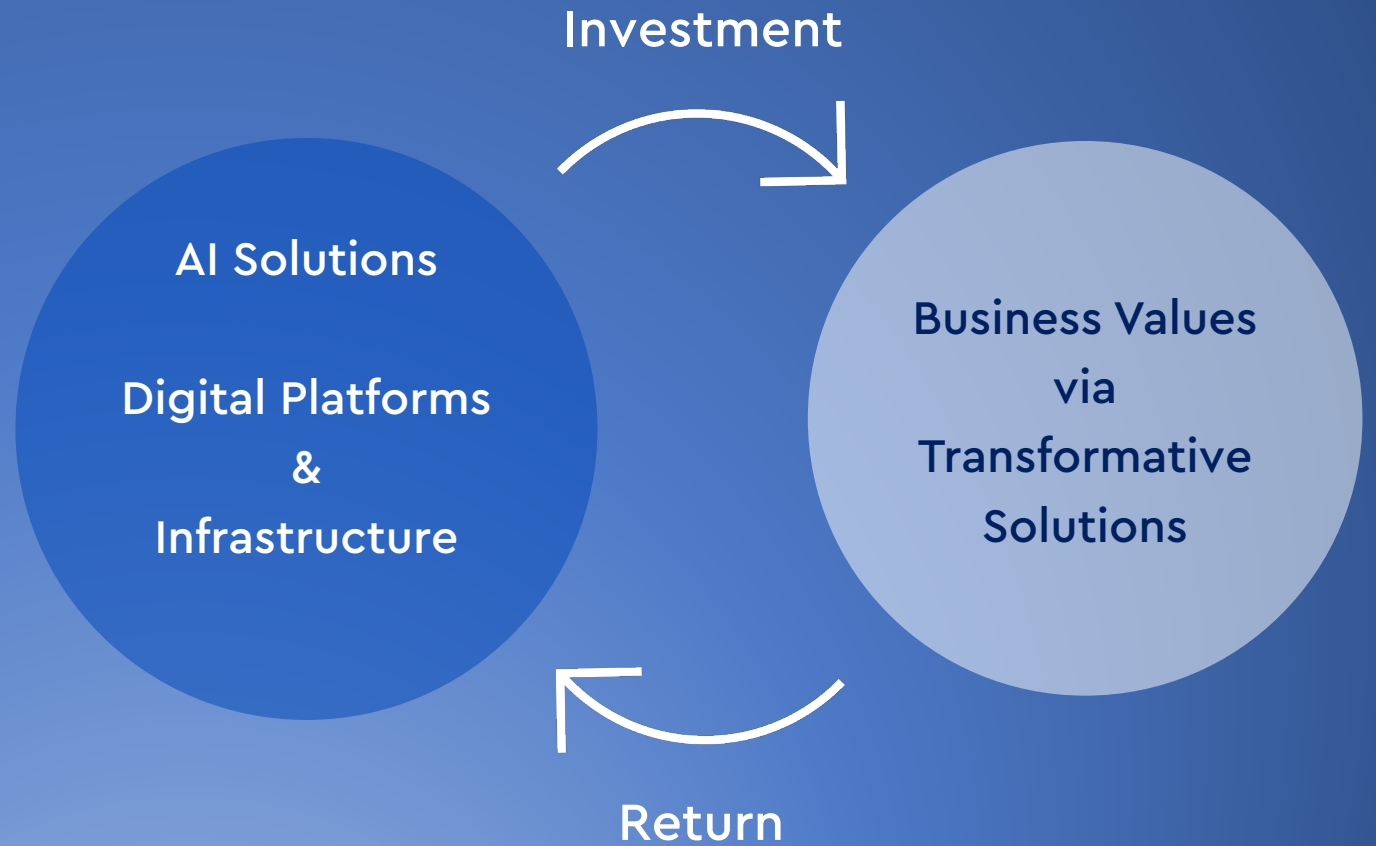


Complexity

**Data Characteristics**

**Virtuous (or Vicious) Cycle**

**Data-centric AI**



"We need 1,000 models for 1,000 problems" – Andrew Ng

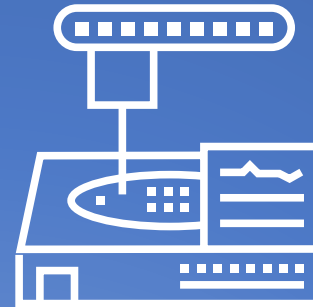
### Data-centric AI

Discipline of systematically engineering the data used to build an AI system

## Data Characteristics

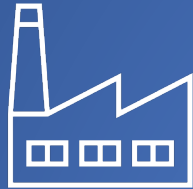
Virtuous (or Vicious) Cycle

**Data-centric AI**



Every company or sector has its own problems

# Our initial focus for 10x changes\*

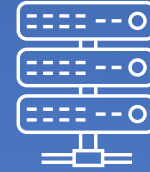


## Semiconductor Fab

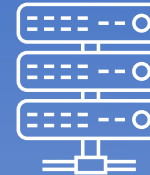
### A modern mega fab has ...

- ~1,000 process equipment
- ~100 metrology equipment
- ~1,000 wafers per day, per equipment
- ~1,000 processes per wafer
- 3-6-month cycle time

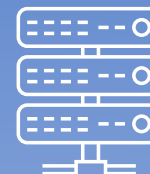
## Servers and Systems



Equipment Sensor Data  
(~1M parameters, ~1Tb/day)



Metrology Image Data  
(~1M images, ~10 Tb/day)



Manufacturing Execution Data  
(~10M events, ~10 Gb/day)

## Why Semiconductor?

Data availability from advanced digitalization

Diverse and sophisticated processes, ideal for expanding to new customers & sectors

Huge impact even within the sector itself

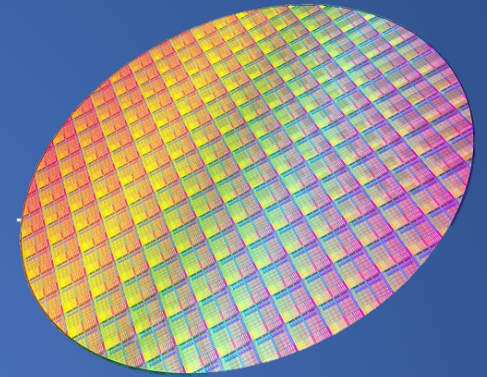


# Computer vision and time-series ML in Manufacturing

## lots of image data to measure and inspect

Scanning electron microscope (SEM) images, transmission electron microscope (TEM) images, etc.

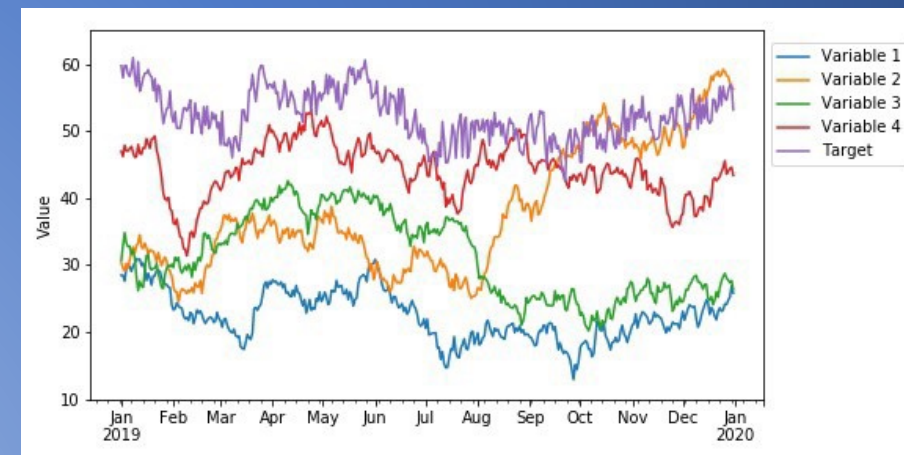
→ Image pattern classification, image anomaly detection, defect inspection, etc.



## (almost) All the data coming from manufacturing are time-series data

Equipment sensor data, process times, material measurement, etc.

→ time-series (TS) regression / prediction/estimation, TS anomaly detection, etc.





# Computer Vision ML for manufacturing



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## **Metrology**

*Measurement of critical features*

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## **Inspection**

*Anomaly detection,  
localization and classification*

Image courtesy of ASML

# Scanning Electron Microscope\*

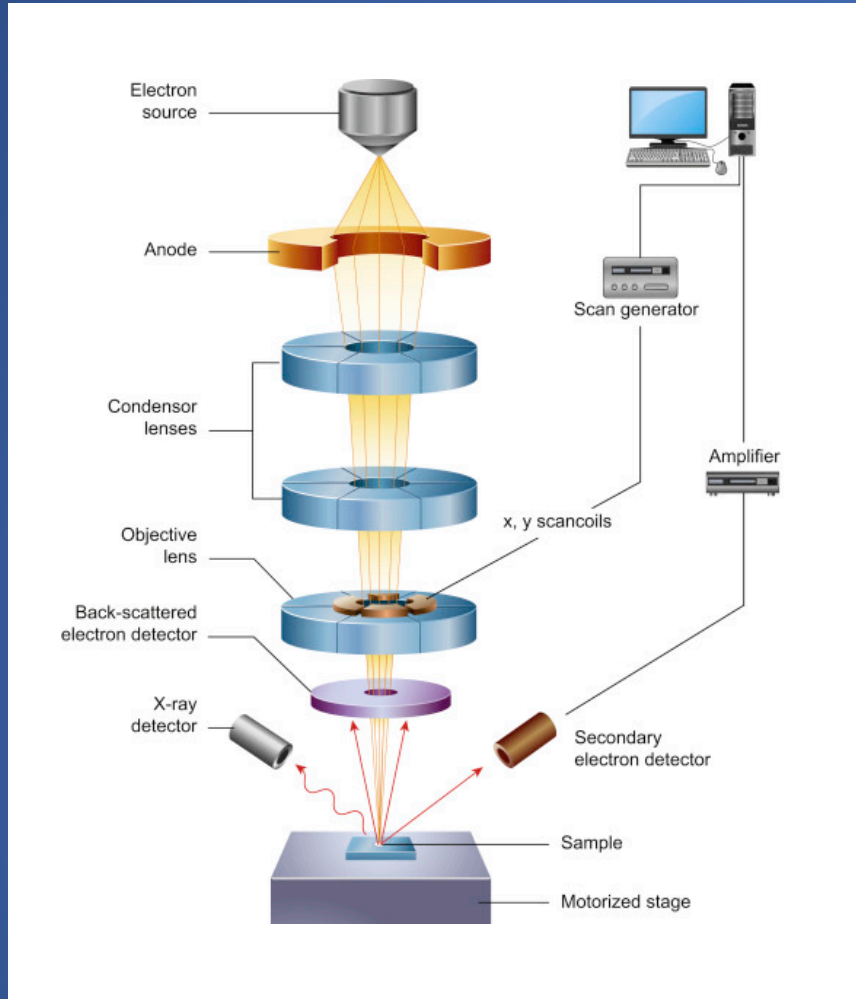
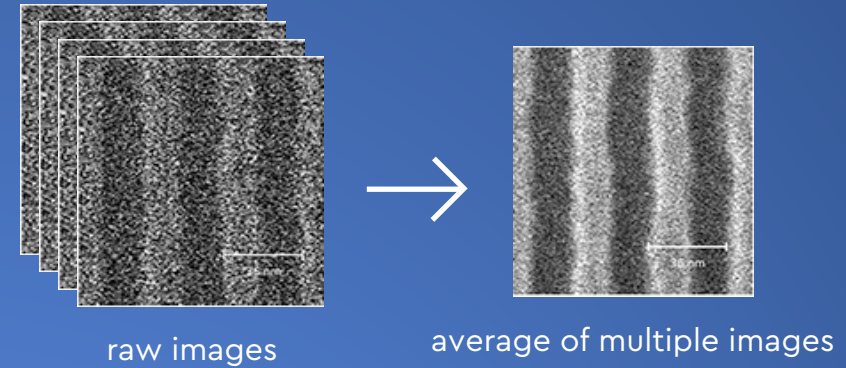


Image courtesy of <https://www.sciencedirect.com/science/article/pii/S9780081000403000002X>



Shot Noise Image courtesy of [https://en.wikipedia.org/wiki/Shot\\_noise](https://en.wikipedia.org/wiki/Shot_noise)



# Image restoration

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## Inverse problem of image corruption

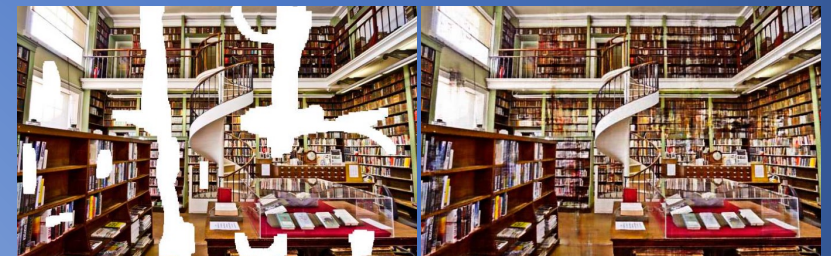
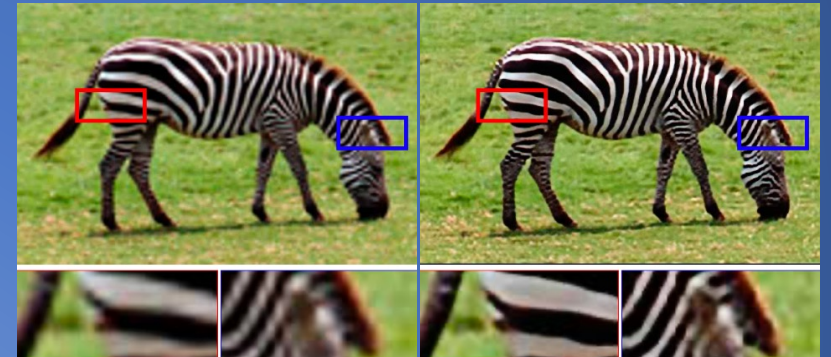
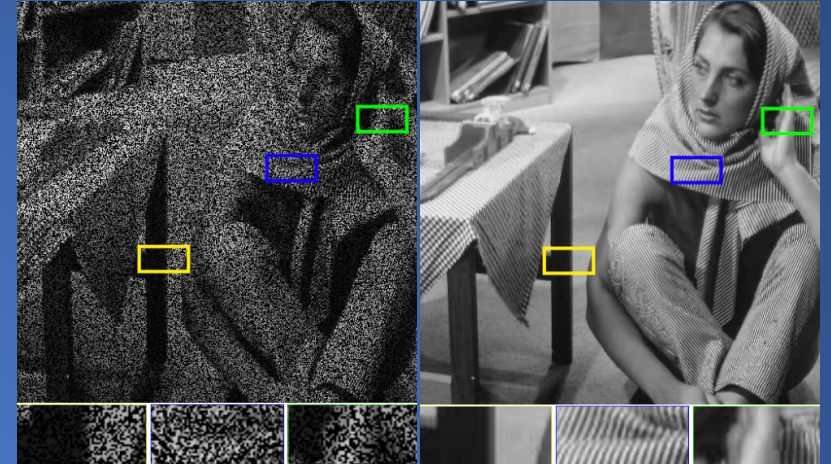
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$$x = f(y) + n$$

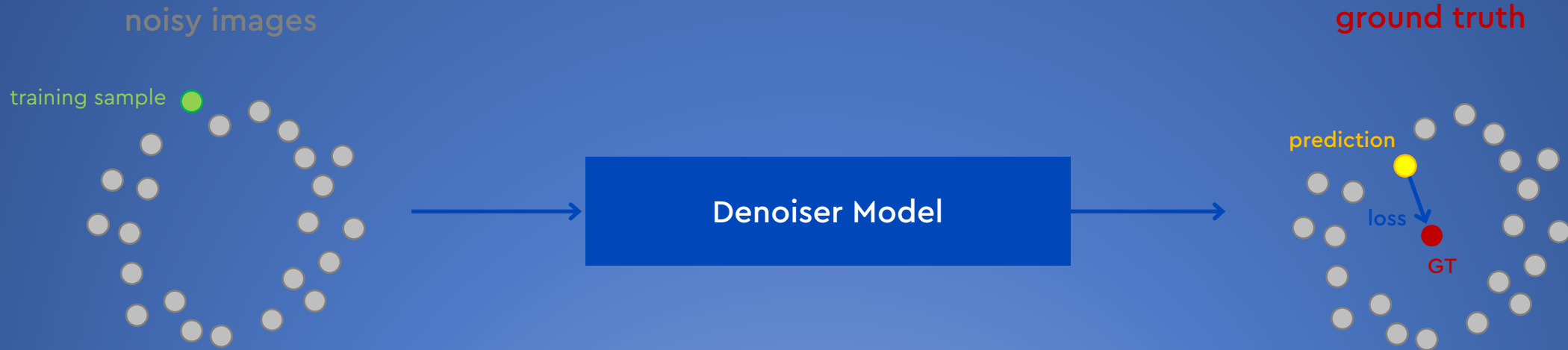
- $y$ : clean image
- $x$ : corrupted image
- $n$ : noise

## $f(\cdot)$ and corresponding solutions

- Noising: Identity function  $\rightarrow$  Denoising
- Downsampling  $\rightarrow$  Super-resolution
- Missing pixels  $\rightarrow$  Inpainting

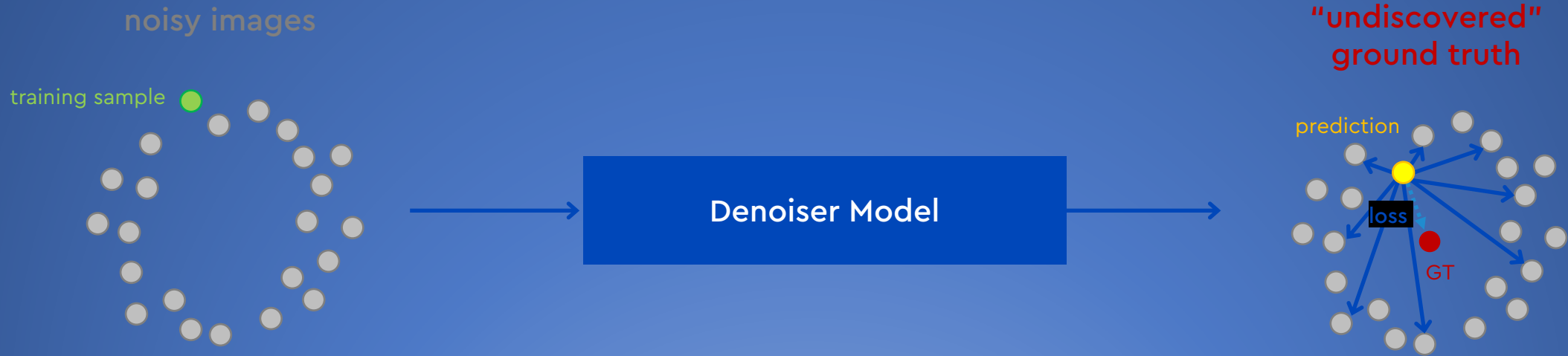


# Supervised image denoising



*However, it is not possible to acquire ground-truth images from SEM device, in practice.*

# Blind denoising without ground truth



*If the mean of the noise is zero, the average of the gradients that model takes is same with the gradient to the ground truth*



# Metrology based on segmentation and pattern recognition

Investment

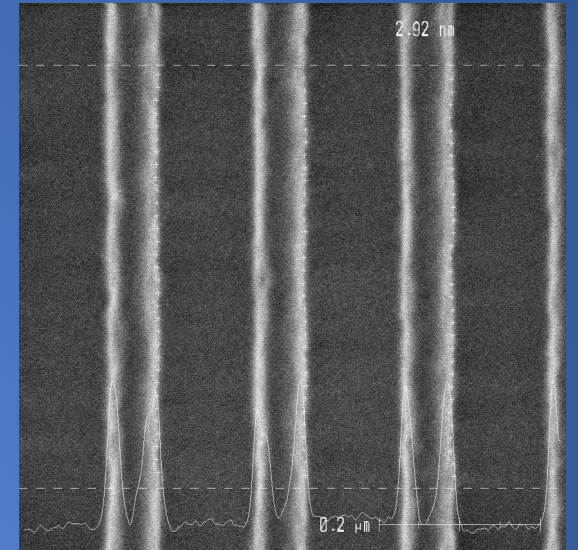
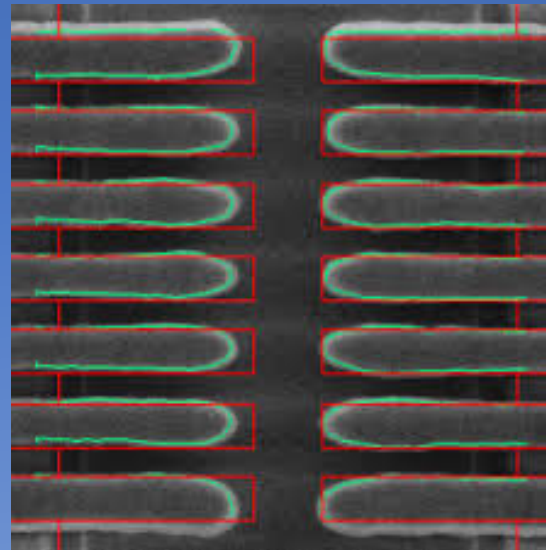
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Automatic measurement of critical dimensions

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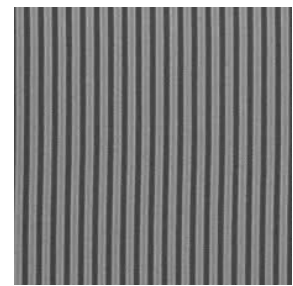
## Approaches

- Unsupervised texture segmentation
- Repetitive pattern recognition

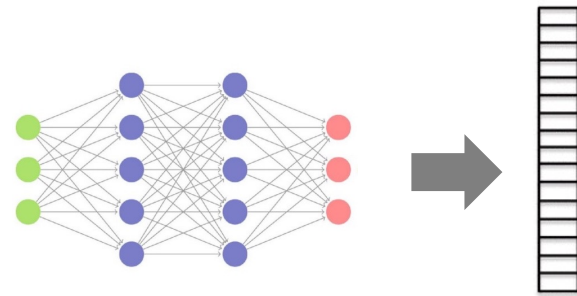
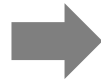


<0.1 nm measurement precision guaranteed

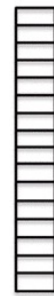
# Anomaly detection in unsupervised learning\*



input image



pretrained NN



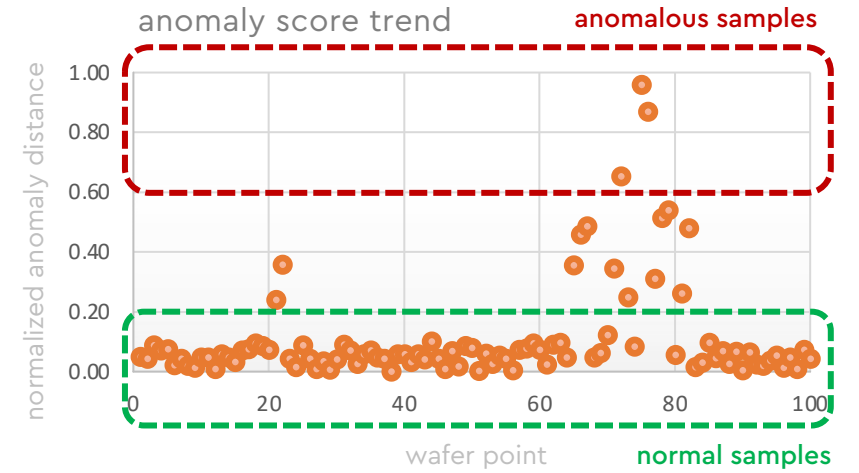
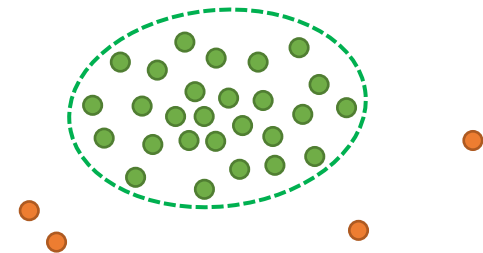
feature vector

distance to the  
normal vector cluster in kNN

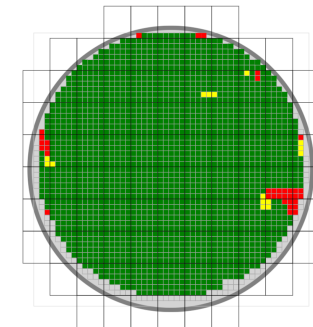


precomputed in  
unsupervised learning

vectors of normal images  
vectors of anomalous images

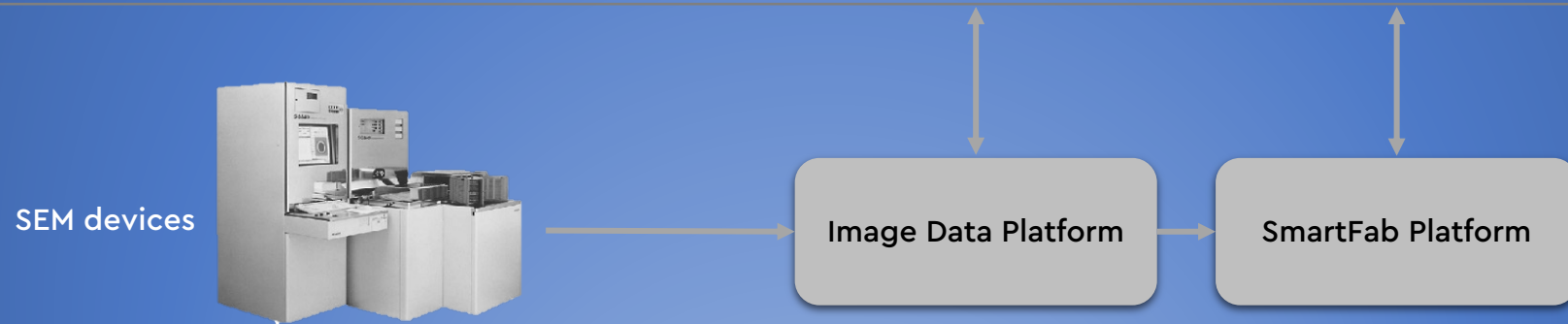
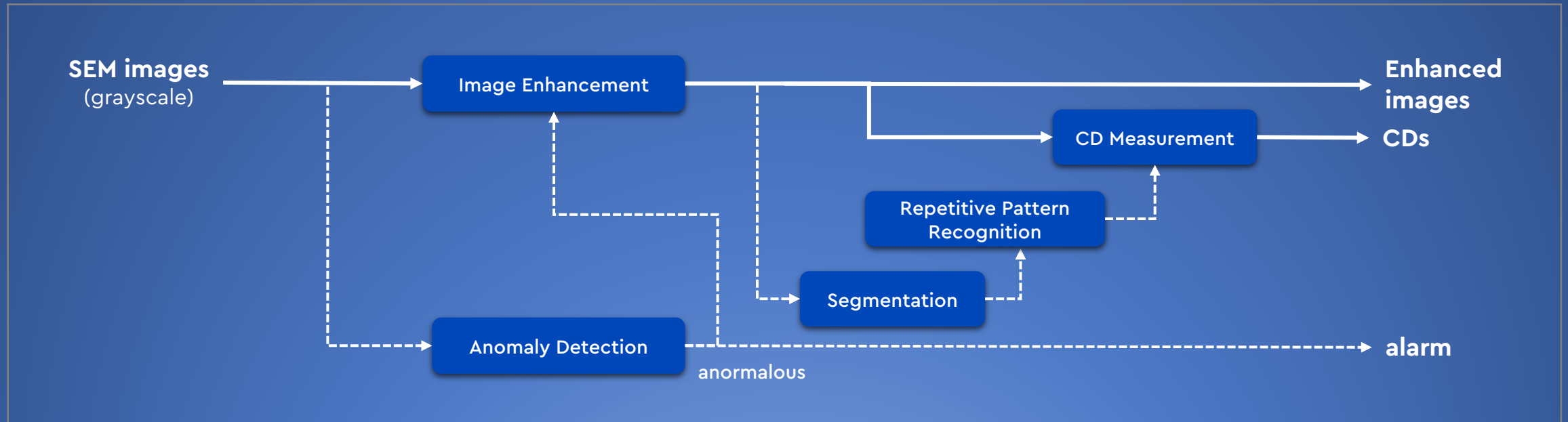


anomaly score  
wafer map





# AI-accelerated metrology system



# Automatic measurement for semiconductor manufacturing

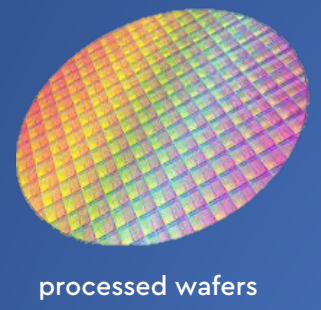


image capture

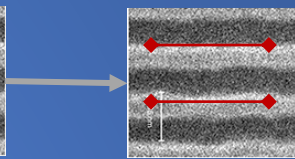
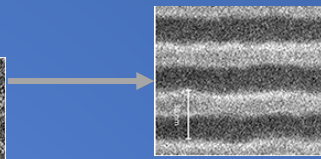
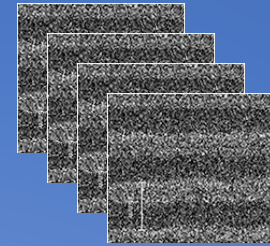
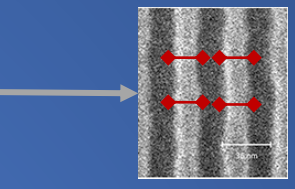
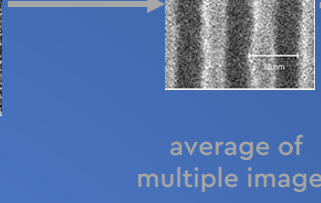
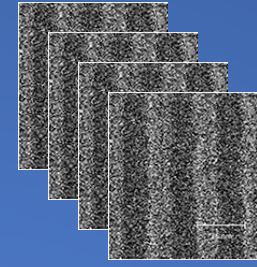
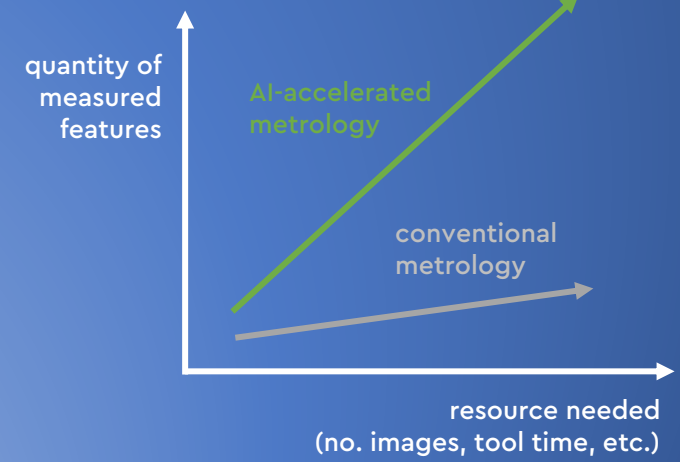
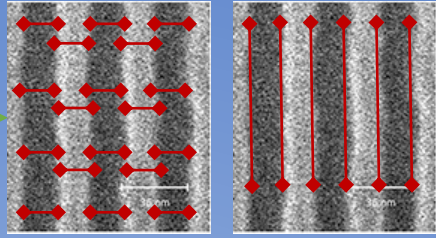
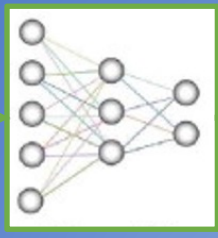
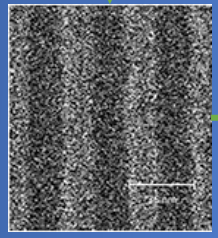


image capture

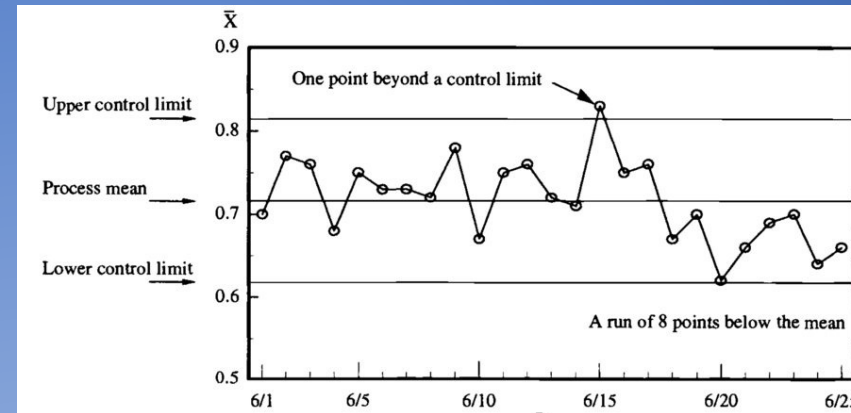
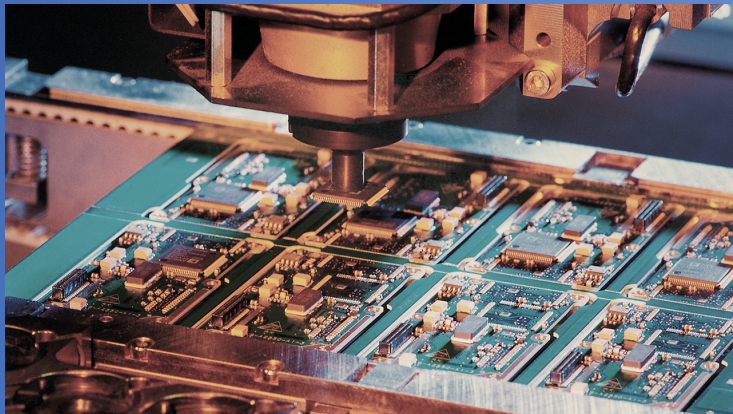


# Time-series ML for manufacturing

# Why time-series ML?

*manufacturing application is about one of the followings:*

- prediction of time-series values - virtual metrology, yield prediction
- classification of time-series values - equipment anomaly alarm generation
- anomaly detection on time-series data - root cause analysis, yield analysis



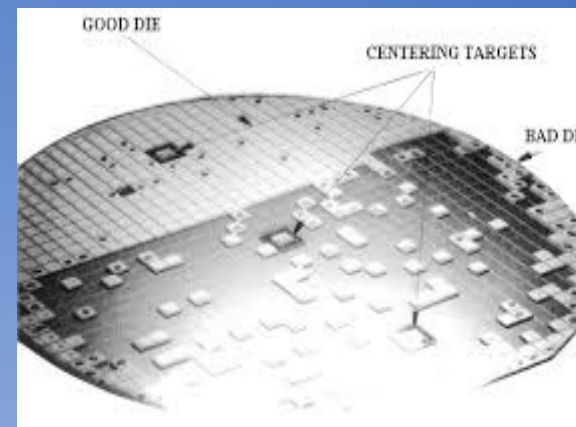
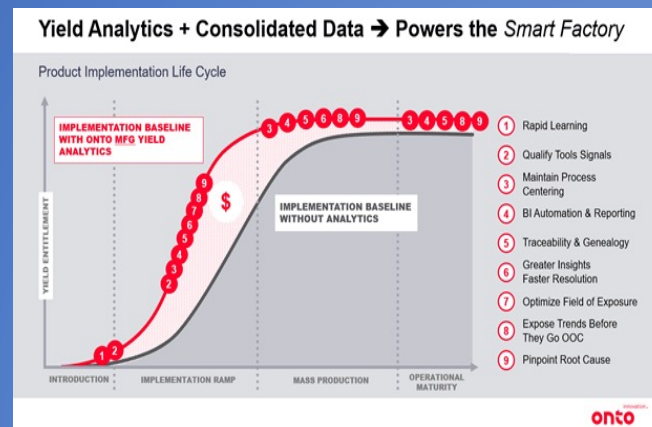
# Time-series regression/prediction/estimation

- virtual metrology

- *measure unmeasured* processed materials using equipment sensor signals
- *save investment on measurement equipment, downstream applications such as process control, statistical process control, yield improvement*

- yield prediction

- *predict yield (# working dies / # total dies)*
- *better product quality and larger profit, business impact*





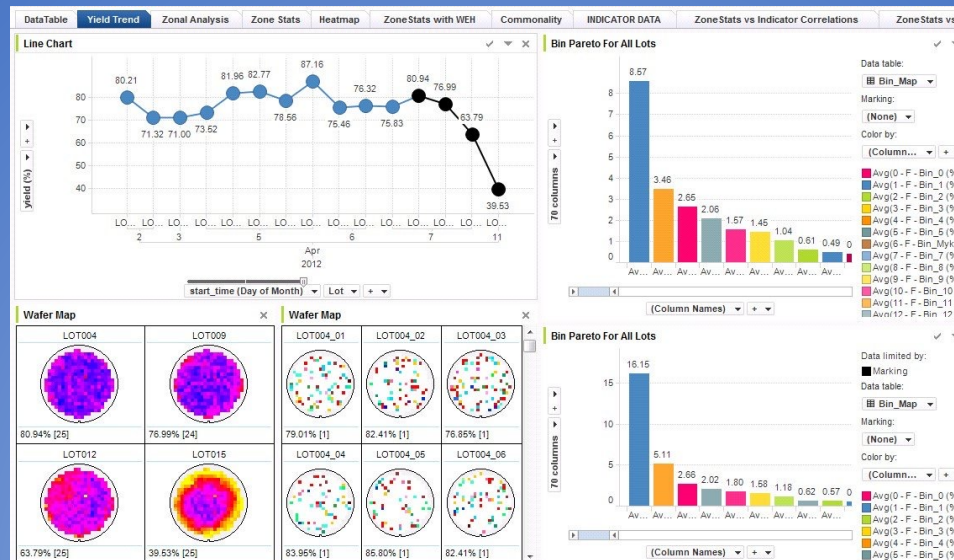
# Root cause analysis using time-series anomaly detection\*

- equipment alarm root cause analysis

- when alarm goes off, find responsible equipment and root causes
- reduce equipment downtime, make *process engineers' lives easier*

- yield analysis

- find responsible equipment and root causes for yield drop
- a few % yield improvement brings profit increase of tens of millions of dollars!



# Difficulties with Time-series ML in manufacturing



# Data challenges

- covariate shift & concept drift

$p(x(t_k), x(t_{k-1}), \dots)$  changes over time

$p(y(t_k) | x(t_k), x(t_{k-1}), \dots, y(t_{k-1}), y(t_{k-2}), \dots)$  changes over time

- fat data, *i.e.*, # features way larger than # data
- poor data quality; missing values, anomalies, wrong formats
- huge volume of data to process
- multi-modality - different types of data

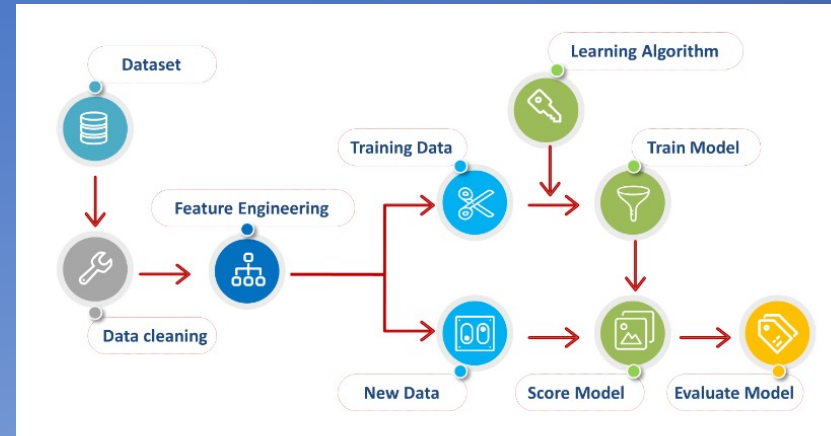
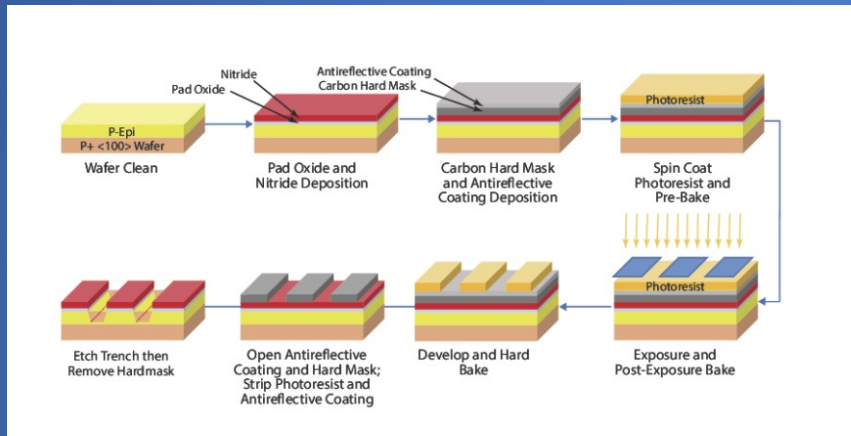
# Domain knowledge and fully home-grown algorithms

*in most cases,  
domain knowledge is critical!*

close collaboration with customers required

*off-the-shelf algorithms  
not working!*

developing fully customized algorithms needed



# Virtual Metrology (VM)

# What is VM?

*in many cases,  
we cannot measure all  
processed materials*

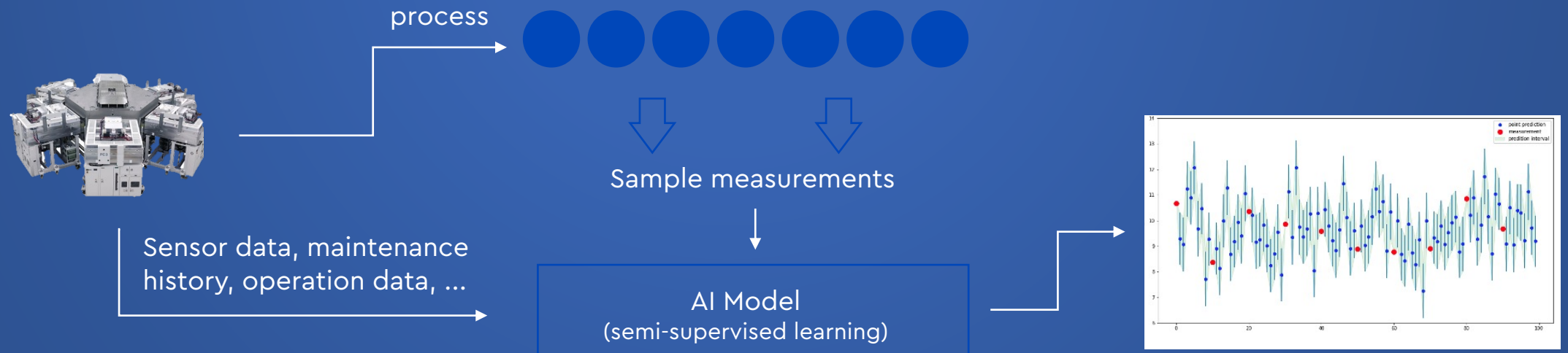
- measurement equipment is too expensive
- measuring every materials makes production slow inducing low throughput

*thus, we do sampling  
(with very low sampling rate)*

- in semiconductor manufacturing line, average sampling rate is less than 5%

## PROBLEM

- predict the measurement of unmeasured material using indirect signals
- sensor data, maintenance history, operation data, . . .



# Business Impact made by VM

## *To the best of our knowledge*

- no organization has even been successful with VM

## **Gauss Labs VM**

- uses online learning to cope with data drift/shift
- RMSE comparable to measurement equipment precision
- also predicts uncertainty of predictions - providing prediction reliability information

## **VM implications**

- measuring ALL wafers – equivalent to investing on 100x measurement equipment
- enables optimal re-allocation of limited measurement resources

# Conclusion

*supervised and  
unsupervised ML  
everywhere in industrial  
AI applications*

*lots of  
challenges*

- data challenge, domain knowledge required, need for customizing algorithms

*huge changes potentially  
made via various  
applications*

## **Impacts**

- Tens of Millions of dollars by 1% yield increase
- 100x measurement equipment save by VM